

United States Patent and Trademark Office

UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

APPLICATION NO.	FIL	ING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/773,615		2/06/2004	Jin-Sung Lee	678-1234 (P11102)	7749
28249	7590	09/29/2005		EXAMINER	
		RESE, LLP	FORD, JOHN K		
333 EARLE OVINGTON BLVD. UNIONDALE, NY 11553				ART UNIT	PAPER NUMBER
00				3753	

DATE MAILED: 09/29/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

		ϵ					
	Application No.	Applicant(s)					
Office Action Commence	10/773,615	LEE ET AL.					
Office Action Summary	Examiner	Art Unit					
	John K. Ford	3753					
The MAILING DATE of this communication app Period for Reply	pears on the cover sheet with the c	correspondence address					
A SHORTENED STATUTORY PERIOD FOR REPLY WHICHEVER IS LONGER, FROM THE MAILING D. - Extensions of time may be available under the provisions of 37 CFR 1.1 after SIX (6) MONTHS from the mailing date of this communication. - If NO period for reply is specified above, the maximum statutory period of Failure to reply within the set or extended period for reply will, by statute Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be tir will apply and will expire SIX (6) MONTHS from to cause the application to become ABANDONE	N. mely filed the mailing date of this communication. ED (35 U.S.C. § 133).					
Status							
1) Responsive to communication(s) filed on	the 14, 2005						
2a)⊠ This action is FINAL . 2b)□ This	This action is FINAL . 2b) ☐ This action is non-final.						
3) Since this application is in condition for allowa	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is						
closed in accordance with the practice under E	closed in accordance with the practice under Ex parte Quayle, 1935 C.D. 11, 453 O.G. 213.						
Disposition of Claims							
4) Claim(s) 1-6 is/are pending in the application.							
4a) Of the above claim(s) $3-5$ is/are withdrawn from consideration.							
5) Claim(s) is/are allowed.	5) Claim(s) is/are allowed.						
6) Claim(s) 1,2	i) Claim(s) 1, 2,6 is/are rejected.						
8) Claim(s) are subject to restriction and/o	or election requirement.						
Application Papers							
9) The specification is objected to by the Examine	er.						
10) The drawing(s) filed on is/are: a) accepted or b) objected to by the Examiner.							
Applicant may not request that any objection to the	drawing(s) be held in abeyance. Se	e 37 CFR 1.85(a).					
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).							
11) ☐ The oath or declaration is objected to by the Ex	caminer. Note the attached Office	Action or form PTO-152.					
Priority under 35 U.S.C. § 119							
12) (Acknowledgment is made of a claim for foreign a) (All b) Some * c) None of:	priority under 35 U.S.C. § 119(a)-(d) or (f).					
1. Certified copies of the priority documents have been received.							
2. Certified copies of the priority documents have been received in Application No							
3. Copies of the certified copies of the priority documents have been received in this National Stage							
application from the International Bureau (PCT Rule 17.2(a)).							
* See the attached detailed Office action for a list of the certified copies not received.							
Attachment(s)							
Notice of References Cited (PTO-892) Notice of Draftsperson's Patent Drawing Review (PTO-948)	4) Interview Summary Paper No(s)/Mail D						
3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)	5) Notice of Informal F	Patent Application (PTO-152)					
Paper No(s)/Mail Date	6)						

Applicant's response of July 14, 2005 has been studied carefully. Claims 1, 2 and 6 are examined here. Applicant's election of the first species of Figure 5, without traverse, is acknowledged, and claims 1, 2 and 6 have been identified as readable on the elected species. Claims 3-5 remain withdrawn as directed to non-elected species.

Applicant argues that the amendment, in the July 14, 2005 response, that recites that the cooling pipe is laid "along the hollow bore" in the heat transfer plate distinguishes claim 1 from the prior art. The Examiner disagrees for reasons that are explained in the rejections that follow.

Applicants apparently are all employed by Samsung and it is of concern that Samsung's JP 2001-93795 or its equivalent was not cited to the Examiner by applicants given that it shows a substantial portion of the independent claim to be well known. In the last office action, applicants were asked if there were any other relevant Samsung prior art publications related to wafer platens having an embedded vaporization/condensation cavity in the system? The July 14, 2005 amendment is silent on the matter. Please address it in any forthcoming response.

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

⁽a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1, 2 and 6 are rejected under 35 U.S.C. 103(a) as being unpatentable over JP 2001-93795 (Figs 22-27) in view of Hisai et al. (US 2003/0192686).

JP '795 (Figs 22-27) shows all of the claimed features except a cooling pipe in the hollow bore(s) 515. A working fluid 540 is shown in the hollow bore(s) 515 in Figure 24. A heater is shown at 524 (Fig. 27). No cooling pipe is shown in the hollow bore(s) 515. For purposes of rejection here the open space 515 between supporting structures 530 shown in cross-section in Figure 24 and in plan view in either of Figures 25 or 26 is deemed to be a "hollow bore" in as much as these Figures have an uncanny resemblance to the "hollow bore" 131 shown in Figure 4 of the present application. The "hollow bore" of the present application appears to be no more than a cavity with a plurality of separators 133 linking the upper surface of element 103 with the lower surface of element 103. This is no different than what Figures 24, 25 and 26 of JP '795 show, i.e. many small division walls 530, with hollow bores (515) clearly formed between these small division walls.

Hisai teaches in the type of working fluid heater disclosed by JP'795, using a cooled pipe 22 located in the sealed chamber containing the working fluid. The chamber has a plurality of "pillars" 13 and there appear to be "hollow bores" formed in these pillars (see the phantom lines under elements 13 in Figure 3) for the cooling pipe 22 to span substantially the entirety of the sealed chamber as shown in Figure 4.

Art Unit: 3753

To have used such a cooling pipe in JP'795 to advantageously permit cooling of the semiconductor would have been obvious. Needless to say, the easiest modification to make to Figures 25 or 26 of JP '795 (i.e. the Samsung prior art system that applicant's here are attempting to modify) would have been to have placed the cooling pipe in the open space 515 between the division walls 530 (i.e. in the hollow bore(s) between the division walls 530). Such a placement would advantageously avoid having to compromise the strength of the device by chopping away at the division walls 530. If applicant contests this logic, please explain where else could one put the cooling pipe in JP '795 and still have it be in the hollow space 515 (Hisai clearly teaches the cooling pipe has to be in the hollow space 12).

Regarding claim 2, specifying the intended level of a working substance in an apparatus does not impart patentability to that apparatus. See <u>In re Masham</u>, 2 USPQ2d 1647 (BPAI 1987).

Claims 1, 2 and 6 are rejected under 35 U.S.C. 103(a) as being unpatentable over JP 2003-53741 (Figure 5) in view of Hisai et al. (US 2003/0192686).

JP '741 shows a cooler 21 and a heater 14 arranged on the backside of a hollow heat transfer plate in Figure 5.

Hisai teaches a cooling pipe 22 located in the sealed chamber of a heat transfer plate.

To have placed a cooling pipe 22 into hollow space 6 of JP '741 in place of element 21 would have been obvious to advantageously make the overall structure smaller and the cooling more efficient.

Claims 1, 2 and 6 are rejected under 35 U.S.C. 103(a) as being unpatentable over any of the prior art as applied to claims 1, 2 and 6 above, and further in view of Foglesonger et al (USP 4,998,584) or Flanigan et al (USP 6,081,414).

To the extent that it is necessary, and the Examiner does not believe that it is, Foglesonger and Flanigan both show that it is known to place or lay a heat exchange tube in a groove (or hollow bore) formed in a plate with the tube having a dimension smaller than the hollow bore that is filled by some intermediate heat transfer substance that carries the heat across the gap between the tube and the wall of the cavity. In the case of Foglesonger this intermediate heat transfer substance is boron nitride in an aqueous carrier and in Flanigan, brazing material, whereas in JP '795 or JP '741 the intermediate heat transfer substance is a perfluorocarbon. Nonetheless, Foglesonger and Flanigan each clearly teaches placing or laying a heat exchange tube in a hollow bore (groove) in a plate surrounded by an intermediate heat carrier, thereby reinforcing the Examiner's logic above.

Claim 2 is rejected under 35 U.S.C. 103(a) as being unpatentable over any of the prior art as applied to claims 1, 2 and 6 above, and further in view of JP 4-338242.

Regarding the placement of the cooling pipe below the level of the working fluid as claimed in claim 2, JP '242 fairly teaches this at the right submerged heat exchanger.

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication should be directed to John Ford at

telephone number (571) 272-4911.

Primary Examiner